



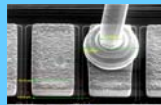
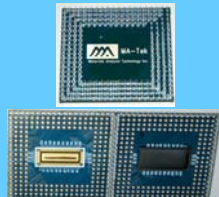
Independent/Professional Analysis Lab, the best partner to your R&D group!!  
Your first choice to product development, quality assurance and IP strategy!!!

## Total Solution for ESD Testing Service

### Wide Span of Service Scope

- Various testing modes [HBM, MM, socket CDM, non-socket CDM, latch-up]
- Room temperature and high temperature testing facility
- Dynamic testing capability - vector input board with high frequency
- BGA package ESD/Latch-up testing capable – various sockets

#### Wire Bonding/Packaging



Pad pitch limit :  
Al > 35um  
Au > 27um(auto), > 24um(manual)



- Wire bonding and packaging services [Au/Al wiring, die mount, epoxy encapsulation]
- COB testing and package level testing
- System level testing of module, mother board, and electronic system by ESD gun

### Customized Service

- Establishment of ESD/Latch-up design rules
- Design of I/O cell library, specific pad circuitry
- Consultancy of ESD protection scheme

New Product Qualification

Ver.1 Bare Die Die Mount

Wire Bonding for Testing

ESD Testing Fail

Failure Analysis

FIB Circuit Modification

ESD Testing & Circuit Verification

Ver.2 Bare Die Die Mount

Mass Production

Product Field Applications

PD Malfunctioning

Failure Analysis & ESD Fault Isolation

Site Auditing

ESD Testing & Fault Re-occurrence

ESD Technical Assessment

Continuous Improvement Program

Class-0 Production ESD Free

Technical Consultant:

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You are highly welcome to use Fedex (account no. 2665-9953-6) , DHL (account no. 968368648) or UPS services for sample shipping. ma-tek pay the courier charge upon sample arrival.



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